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Mechanical Engineering
Effective Date: January 1, 2017

BIBLIOGRAPHY

I. Refereed Publications

A. Archival Journals


9) Vishwakarma, V., et al., 2015, “Heat transfer enhancement in a lithium-ion cell through improved material-level thermal transport,” J. of Power Sources, Vol. 30, 123


*New Since Last Review

*New Since Last Review
41) Tyagi, H., Phelan, P.E., Prasher, R.S., Peck, R., Lee, T, Pacheco, J.R, and

*New Since Last Review


*New Since Last Review

*New Since Last Review
Thermal Interface Material on Particle Volume Fraction,” Journal of Electronics Packaging, vol. 125, No. 3

B. Refereed Conference and Symposium Proceedings

*New Since Last Review


*New Since Last Review


*New Since Last Review


34) Cho, E.S., Koo, Jae-Mo, Jiang, L., Prasher, R.S., Kim, M.S., Santiago, J.G., Kenny, T.W., and Goodson, K.E., 2003“Experimental Study of Two Phase


*New Since Last Review

46) Prasher, R.S., Simmons, C, and Solbrekken, G., 2000 “Thermal Contact Resistance of Phase Change and Grease Type Polymeric Materials,” proceedings of the International Mechanical Engineering Congress and Exposition, Orlando, Florida


II. Non-refereed Publications

A. Technical Reports

1.

B. Non-Refereed Conference and Symposium Proceedings

1.

C. Articles in Nonarchival Magazines or Journals


III. Books

*New Since Last Review
IV. Book Chapters


V. Other (e.g., Patents)

<table>
<thead>
<tr>
<th>PAT. NO.</th>
<th>Title</th>
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</thead>
<tbody>
<tr>
<td>1 7,957,137</td>
<td>Method for cooling an integrated circuit die with coolant flow in a microchannel and a thin film thermoelectric cooling device in the microchannel</td>
</tr>
<tr>
<td>2 7,633,752</td>
<td>Cooling an integrated circuit die with coolant flow in a microchannel and a thin film thermoelectric cooling device in the microchannel</td>
</tr>
<tr>
<td>3 7,576,432</td>
<td>Using external radiators with electroosmotic pumps for cooling integrated circuits</td>
</tr>
<tr>
<td>4 7,498,672</td>
<td>Micropin heat exchanger</td>
</tr>
<tr>
<td>5 7,435,623</td>
<td>Integrated micro channels and manifold/plenum using separate silicon or low-cost polycrystalline silicon</td>
</tr>
<tr>
<td>6 7,365,980</td>
<td>Micropin heat exchanger</td>
</tr>
<tr>
<td>7 7,309,453</td>
<td>Coolant capable of enhancing corrosion inhibition, system containing same, and method of manufacturing same</td>
</tr>
<tr>
<td>8 7,259,965</td>
<td>Integrated circuit coolant microchannel assembly with targeted channel configuration</td>
</tr>
<tr>
<td>9 7,253,523</td>
<td>Reworkable thermal interface material</td>
</tr>
<tr>
<td>10 7,243,705</td>
<td>Integrated circuit coolant microchannel with compliant cover</td>
</tr>
<tr>
<td>11 7,218,519</td>
<td>Thermal management arrangement with a low heat flux channel flow coupled to high heat flux channels</td>
</tr>
</tbody>
</table>

*New Since Last Review
12 7,212,405 Method and apparatus for providing distributed fluid flows in a thermal management arrangement
13 7,115,987 Integrated stacked microchannel heat exchanger and heat spreader
14 7,104,313 Apparatus for using fluid laden with nanoparticles for application in electronic cooling
15 7,071,552 IC die with directly bonded liquid cooling device
16 7,031,159 Parallel heat exchanger for a component in a mobile system
17 6,992,382 Integrated micro channels and manifold/plenum using separate silicon or low-cost polycrystalline silicon
18 6,992,381 Using external radiators with electroosmotic pumps for cooling integrated circuits
19 6,981,849 Electro-osmotic pumps and micro-channels
20 6,934,154 Micro-channel heat exchangers and spreaders
21 6,906,919 Two-phase pumped liquid loop for mobile computer cooling
22 6,903,930 Parallel heat exchanger for a component in a mobile system
23 6,903,929 Two-phase cooling utilizing microchannel heat exchangers and channeled heat sink
24 6,751,837 Method of heat extraction from an integrated circuit die
25 6,696,635 Thermoelectrically cooling electronic devices
26 6,661,660 Integrated vapor chamber heat sink and spreader and an embedded direct heat pipe attachment
27 6,639,799 Integrated vapor chamber heat sink and spreader and an embedded direct heat pipe attachment
28 6,625,022 Direct heatpipe attachment to die using center point loading
29 6,535,386 Electronic assembly having a heat pipe that conducts heat from a semiconductor die
30 6,504,721 Thermal cooling apparatus
31 6,469,893 Direct heatpipe attachment to die using center point loading
32 6,381,135 Loop heat pipe for mobile computers
33 6,365,821 Thermoelectrically cooling electronic devices
34 6,351,387 System and method of heat extraction from an integrated circuit die
35. 0133814 A1 Fuel-Flexible Thermal Power Generator For Electric Loads
36 / 0366629 A1 Thermoelectric Device for High Temperature Applications

*New Since Last Review